

## Description

The HSS0038A is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

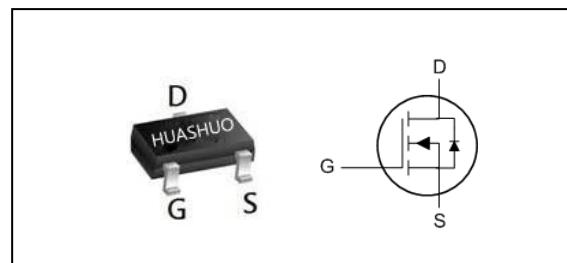
The HSS0038A meet the RoHS and Green Product requirement with full function reliability approved.

- Green Device Available
- Rugged and Reliable
- Switching Application
- Advanced high cell density Trench technology

## Product Summary

V <sub>DS</sub>	100	V
R <sub>DS(ON),max</sub>	6	Ω
I <sub>D</sub>	0.18	A

## SOT23 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1</sub>	0.18	A
I <sub>DM</sub>	Pulsed Drain Current(note 1)	0.68	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sub>3</sub>	0.36	W
I <sub>S</sub>	Continous Source-Drain Diode Current	0.17	A
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient(steady state) <sub>1</sub>	---	357	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $\text{I}_D=1\text{mA}$	---	0.122	---	$\text{V}/^\circ\text{C}$
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=0.22\text{A}$	---	3.6	6	$\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=0.22\text{A}$	---	3.9	10	$\Omega$
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=250\mu\text{A}$	1	1.6	2.8	V
$\Delta \text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-4.84	---	$\text{mV}/^\circ\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=100\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$\text{V}_{\text{DS}}=100\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	100	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 50$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}$ , $\text{I}_D=170\text{mA}$	80	---	---	$\text{mS}$
$\text{Q}_{\text{g}}$	Total Gate Charge	$\text{V}_{\text{DD}}=10\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=0.22\text{A}$	---	1.3	---	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	0.18	---	$\text{nC}$
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	0.21	---	$\text{nC}$
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=30\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_G=50\Omega$	---	---	7	$\text{ns}$
$\text{T}_r$	Rise Time		---	---	7	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	---	12	
$\text{T}_f$	Fall Time		---	---	14	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=25\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	28	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	14	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	3	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sup>1,4</sup>	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	0.17	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=0.44\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.4	V

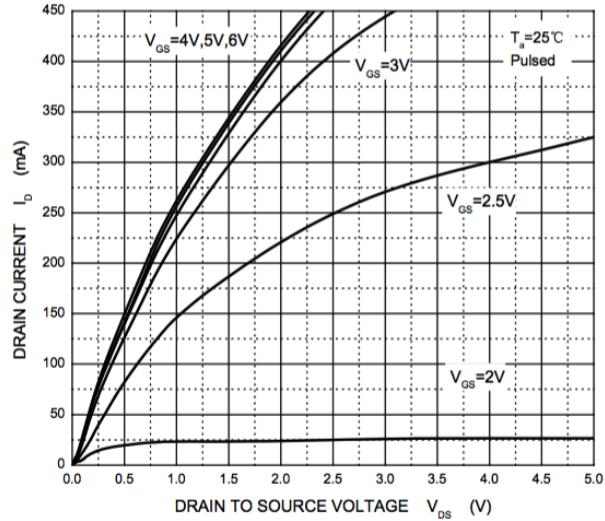
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

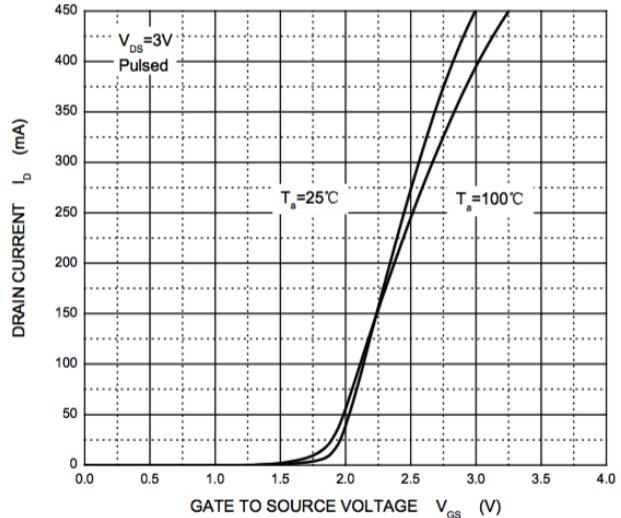


### Typical Characteristics

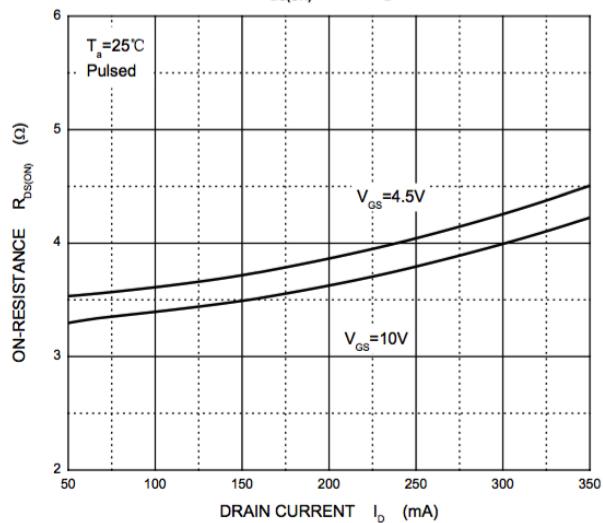
Output Characteristics



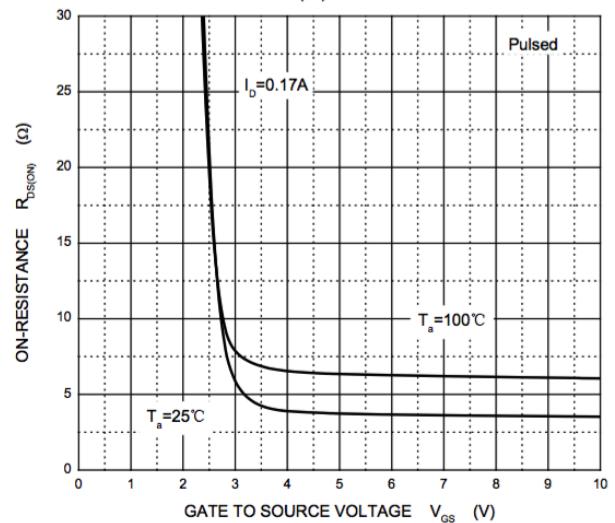
Transfer Characteristics



$R_{DS(ON)}$  —  $I_D$



$R_{DS(ON)}$  —  $V_{GS}$

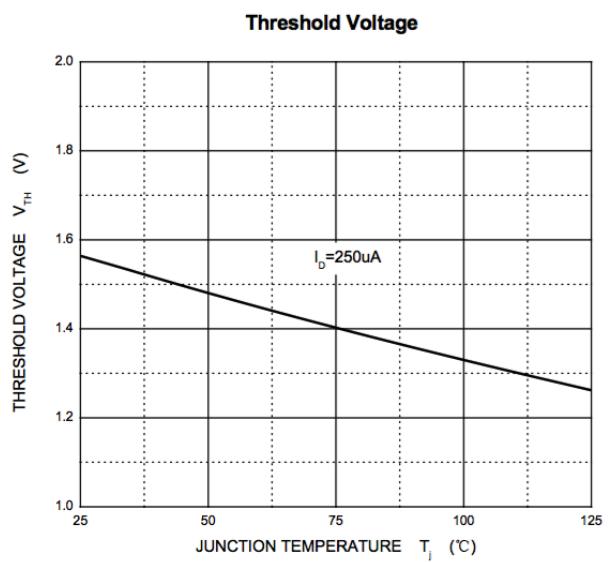
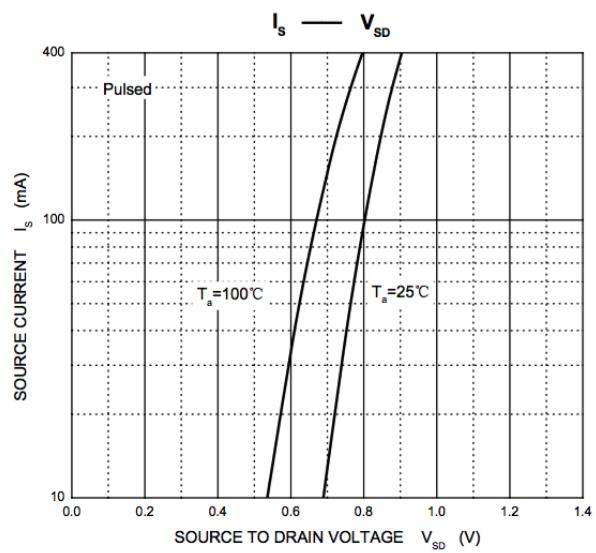




**HUASHUO**  
SEMICONDUCTOR

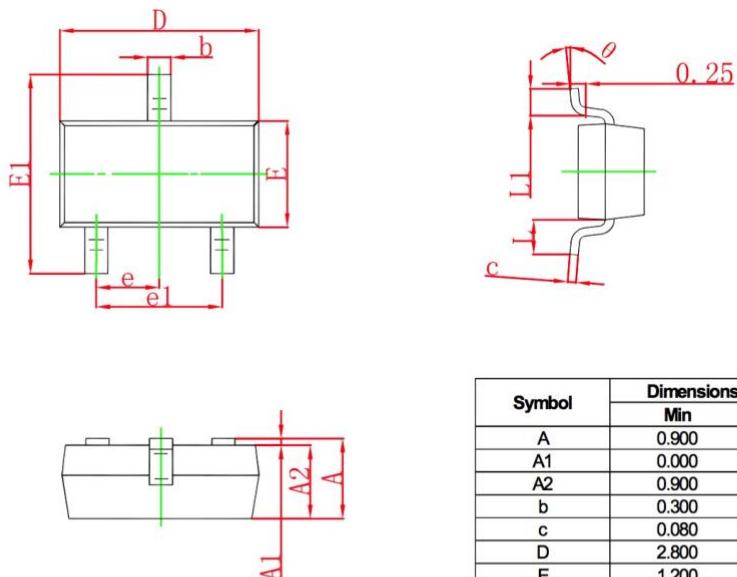
**HSS0038A**

**N-Ch 100V Small-Signal-Transistor**



## Ordering Information

Part Number	Package code	Packaging
HSS0038A	SOT-23	3000/Tape&Reel



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°